**Amendments to the Specification:**

Please replace paragraph [0027] on pages 11-12 with the following amended paragraph:

**[0027]** Generally, injection layers are comprised of a material that may improve the injection of charge carriers from one layer, such as an electrode or an organic layer, into an adjacent organic layer. Injection layers may also perform a charge transport function. In device 100, hole injection layer 120 may be any layer that improves the injection of holes from anode 115 into hole transport layer 125. CuPc is an example of a material that may be used as a hole injection layer from an ITO anode 115, and other anodes. In device 100, electron injection layer 150 may be any layer that improves the injection of electrons into electron transport layer 145. LiF / Al is an example of a material that may be used as an electron injection layer into an electron transport layer from an adjacent layer. Other materials or combinations of materials may be used for injection layers. Depending upon the configuration of a particular device, injection layers may be disposed at locations different than those shown in device 100. More examples of injection layers are provided in United States Patent ~~Application Publication~~ No. ~~2004/0174116~~ 7,071,615, which is incorporated by reference in its entirety. A hole injection layer may comprise a solution deposited material, such as a spin-coated polymer, e.g., PEDOT:PSS, or it may be a vapor deposited small molecule material, e.g., CuPc or MTDATA.

Please replace paragraph [0029] on pages 13 with the following amended paragraph:

**[0029]** A protective layer may be used to protect underlying layers during subsequent fabrication processes. For example, the processes used to fabricate metal or metal oxide top electrodes may damage organic layers, and a protective layer may be

used to reduce or eliminate such damage. In device 100, protective layer 155 may reduce damage to underlying organic layers during the fabrication of cathode 160. Preferably, a protective layer has a high carrier mobility for the type of carrier that it transports (electrons in device 100), such that it does not significantly increase the operating voltage of device 100. CuPc, BCP, and various metal phthalocyanines are examples of materials that may be used in protective layers. Other materials or combinations of materials may be used. The thickness of protective layer 155 is preferably thick enough that there is little or no damage to underlying layers due to fabrication processes that occur after organic protective layer 160 is deposited, yet not so thick as to significantly increase the operating voltage of device 100. Protective layer 155 may be doped to increase its conductivity. For example, a CuPc or BCP protective layer 160 may be doped with Li. A more detailed description of protective layers may be found in United States Patent ~~Application Publication~~ No. ~~2004/0174116~~ 7,071,615, which is incorporated by reference in its entirety.

Please replace paragraph [0054] on page 20 with the following amended paragraph:

**[0054]** In one embodiment of the invention, the organic enhancement layer may include a material which comprises at least one ligand of Formula I and a metal ion such that the resulting material has (i) an oxygen-metal bond and (ii) the nitrogen of ring A is coordinated to the metal. Thus the ~~emissive~~ organic enhancement layer materials of the present invention comprise a partial structure of formula (III):